

Product / Process Change Notification



N° 2020-009-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity Extension by Introduction of 300mm Wafer Diameter for Dedicated OptiMOS™5 Products in PG-TSON-8 package at Infineon Technologies Dresden, Germany

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **6. August 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip20009_a

► **Detailed Change Information:**

Subject: Introduction of 300mm wafer diameter at Infineon Technologies Dresden GmbH

Reason: Next phase of Front End capacity expansion by introduction of 300mm wafer diameter to support continuous increasing customer demand

Description:	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria (200mm) <p><i>and</i></p> <ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria (300mm)	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria (200mm) <p><i>and</i></p> <ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach, Austria (300mm) <p><i>and</i></p> <ul style="list-style-type: none">■ Infineon Technologies Dresden GmbH, Germany (300mm)

► **Product Identification:** External traceability is assured via waferlot number & country of diffusion

► **Impact of Change:**

NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

NO change in existing datasheet parameters

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification

► **Attachments:** Affected product list 1_cip20009_a

► **Time Schedule:**

- | | |
|-------------------------------|---|
| ■ Final qualification report: | on request |
| ■ First samples available: | 15-July-2020 |
| ■ Intended start of delivery: | 25-September-2020 or earlier upon customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.

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Capacity Extension by Introduction of 300mm Wafer Diameter for Dedicated OptiMOS™5
Products in PG-TSON-8 package at Infineon Technologies Dresden, Germany



Sales name	SP number	OPN	Package
BSC012N06NS	SP001645312	BSC012N06NSATMA1	PG-TSON-8-3
BSC021N08NS5	SP001793410	BSC021N08NS5ATMA1	PG-TSON-8-3
BSC027N10NS5	SP001795088	BSC027N10NS5ATMA1	PG-TSON-8-3